# YIBO LIN

University of Texas at Austin, Austin, TX 78712 \$\display\$ University of Texas at Austin yibolin@utexas.edu \$\display\$ www.cerc.utexas.edu/~yibolin

PhD student \$\display\$ Department of Eletrical & Computer Engineering

#### RESEARCH INTERESTS

Nanometer IC design for manufacturability, modeling and optimization in VLSI CAD

### **EDUCATION**

## University of Texas at Austin, TX, USA

Aug. 2013 - Present

Ph.D. student, Department of Electrical and Computer Engineering

Advisor: David Z. Pan

(GPA 3.96/4.0)

#### Shanghai Jiao Tong University, Shanghai, P.R.China

Sep. 2009 - Jun. 2013

B.S., Department of Microelectronics

(GPA 91.17/100) (Rank top 1/60)

EXPERIENCE

# IMEC, Leuven, Belgium

Sep. 2016 - Nov. 2016

Internship

Design technology co-optimization for emerging lithography options

#### Chinese University of Hong Kong, China

Jun. 2016 - Aug. 2016

Summer Intern

Quantum computing

## Cadence Design System, TX, USA

May 2015 - Aug. 2015

Summer Intern

Routability driven detailed placement

### Oracle Inc., TX, USA

May 2014 - Aug. 2014

Summer Intern

Incremental timing driven detailed placement

## ECE Department, University of Texas at Austin, TX, USA

Jan. 2014 - Present

Graduate Research Assistant

Multiple patterning lithography layout decomposition

Stitch aware detailed placement

Triple-patterning aware detailed placement

Dummy fill insertion

Detailed-routing-driven placement

## **PUBLICATIONS**

#### Journal Papers

- [J2] Yu, Bei and Xu, Xiaoqing and Roy, Subhendu and **Lin, Yibo** and Ou, Jiaojiao and Pan, David Z., "Design for manufacturability and reliability in extreme-scaling VLSI", Science China Information Sciences, 2016. (**Invited paper**)
- [J1] Yu, Bei and Xu, Xiaoqing and Gao, Jhih-Rong and Lin, Yibo and Li, Zhuo and Alpert, Charles and Pan, David Z., "Methodology for standard cell compliance and detailed placement for triple patterning lithography", IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD), May, 2015.

## Conference Papers

- [C9] Ou, Jiaojiao and Yu, Bei and Xu, Xiaoqing and Mitra, Joydeep and Lin, Yibo and Pan, David Z., "DSAR: DSA aware routing with simultaneous DSA guiding pattern and double patterning assignment", ACM International Symposium on Physical Design (ISPD), Portland, OR, Mar 19-22, 2017.
- [C8] Lin, Yibo and Yu, Bei and Xu, Xiaoqing and Gao, Jhih-Rong and Viswanathan, Natarajan and Liu, Wen-Hao and Li, Zhuo and Alpert, Charles J and Pan, David Z., "MrDP: Multiple-row detailed placement of heterogeneous-sized cells for advanced nodes", IEEE/ACM International Conference on Computer-Aided Design (ICCAD), Austin, TX, Nov 7-10, 2016.
- [C7] Tao, Yudong and Yan, Changhao and Lin, Yibo and Wang, Sheng-Guo and Pan, David Z. and Zeng, Xuan, "A novel unified dummy fill insertion framework with SQP-based optimization method", IEEE/ACM International Conference on Computer-Aided Design (ICCAD), Austin, TX, Nov 7-10, 2016.
- [C6] **Lin, Yibo** and Yu, Bei and Pan, David Z., "Detailed placement in advanced technology nodes: a survey", IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT), Hangzhou, China, Oct 25-28, 2016. (**Invited paper**)
- [C5] Lin, Yibo and Xu, Xiaoqing and Yu, Bei and Baldick, Ross and Pan, David Z., "Triple/quadruple patterning layout decomposition via novel linear programming and iterative rounding", Proceedings of SPIE, San Jose, CA, Feb 21-25, 2016. (Best Student Paper Award)
- [C4] Lin, Yibo and Yu, Bei and Zou, Yi and Li, Zhuo and Alpert, Charles J and Pan, David Z., "Stitch aware detailed placement for multiple e-beam lithography", IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC), Macau, China, Jan 25-28, 2016.
- [C3] Lin, Yibo and Yu, Bei and Xu, Biying and Pan, David Z., "Triple patterning aware detailed placement toward zero cross-row middle-of-line conflict", IEEE/ACM International Conference on Computer-Aided Design (ICCAD), Austin, TX, Nov 2-6, 2015.
- [C2] Lin, Yibo and Yu, Bei and Pan, David Z., "High performance dummy fill insertion with coupling and uniformity constraints", ACM/IEEE Design Automation Conference (DAC), San Francisco, CA, Jun 7-11, 2015.
- [C1] Pan, David Z. and Liebmann, Lars and Yu, Bei and Xu, Xiaoqing and Lin, Yibo, "Pushing multiple patterning in sub-10nm: are we ready?", ACM/IEEE Design Automation Conference (DAC), San Francisco, CA, Jun 7-11, 2015. (Invited Paper)

## RELATED COURSES

• EE382M: VLSI I	Prof. Michael Orshansky
• EE382N: Computer Architecture	Prof. Aater Suleman
• EE382V: Optimization Issues in VLSI CAD	Prof. David Pan
• EE382M: VLSI II	Prof. Jacob Abraham
• EE380L: Engineer Programming Languages	Prof. Craig Chase
• EE382V: Nanometer Scale IC Design	Prof. Michael Orshansky
• EE382V: VLSI Physical Design Automation	Prof. David Pan
• EE381V: Advanced Algorithms	Prof. Evdokia Nikolova
• EE382V: Advanced Programming Tools	Prof. Aziz Adnan
• EE380N: Optimization in Engineering Systems	Prof. Ross Baldick
• CS383C: Numerical Analysis: Linear Algebra	Prof. Robert van de Geijn

#### **SKILLS**

Programming Languages C/C++, Python, Verilog

Web Development

HTML5, JavaScript/jQuery

## EDA Tools

Cadence Virtuoso, Synopsys Design Compiler, Synopsys IC Compiler

## AWARDS AND HONORS

Franco Cerrina Memorial Best Student Paper Award	SPIE	2016
A. Richard Newton Young Student Fellow	DAC	2014
National Scholarship	Shanghai Jiao Tong University	2012
Samsung Scholarship	Shanghai Jiao Tong University	2011
The Second Prize Scholarship	Shanghai Jiao Tong University	2010